

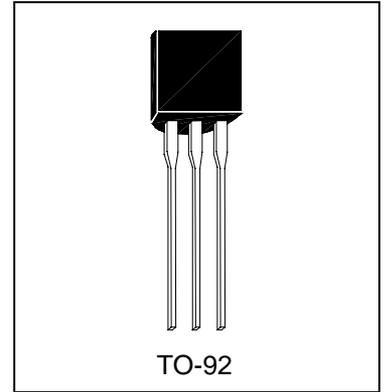


# HSA1538S

PNP EPITAXIAL PLANAR TRANSISTOR

## Description

The HSA1538S is designed for use in high-definition CRT display video output, wide-band amplifier applications..



## Absolute Maximum Ratings

- Maximum Temperatures
  - Storage Temperature ..... -55 ~ +150 °C
  - Junction Temperature ..... +150 °C Maximum
- Maximum Power Dissipation
  - Total Power Dissipation (Ta=25°C) ..... 900 mW
- Maximum Voltages and Currents (Ta=25°C)
  - VCBO Collector to Base Voltage ..... -120 V
  - VCEO Collector to Emitter Voltage ..... -120 V
  - VEBO Emitter to Base Voltage ..... -3 V
  - IC Collector Current ..... -200 mA
  - Icp Peak Collector Current ..... -400 mA

## Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-120	-	-	V	IC=-10uA, IE=0
BVCEO	-120	-	-	V	IC=-1mA, IB=0
BVEBO	-3	-	-	V	IE=-100uA, IC=0
ICBO	-	-	-0.1	uA	VCB=-80V, IE=0
IEBO	-	-	-0.1	uA	VEB=-2V, IC=0
*VCE(sat)	-	-	-1	V	IC=-30mA, IB=-3mA
*VBE(sat)	-	-	-1	V	IC=-30mA, IB=-3mA
*hFE1	60	160	320		VCE=-10V, IC=-10mA
*hFE2	40	-	-		VCE=-10V, IC=-100mA
fT	-	400	-	MHz	VCE=-10V, IC=-50mA
Cob	-	2.8	-	pF	VCB=-30V, f=1MHz

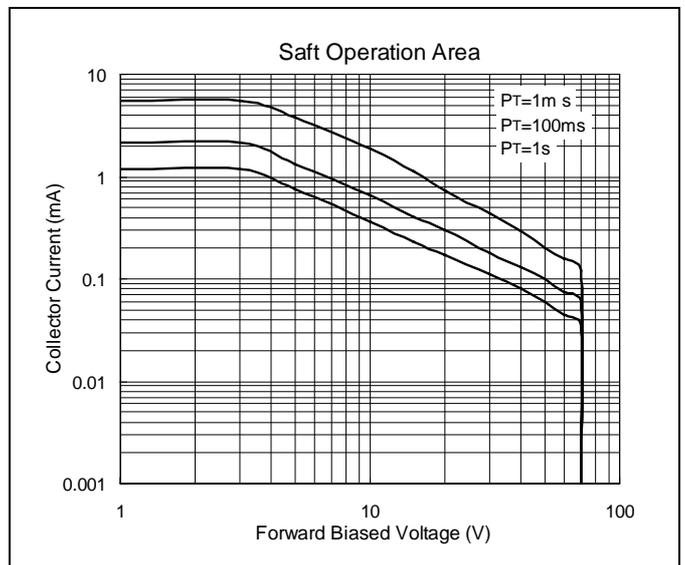
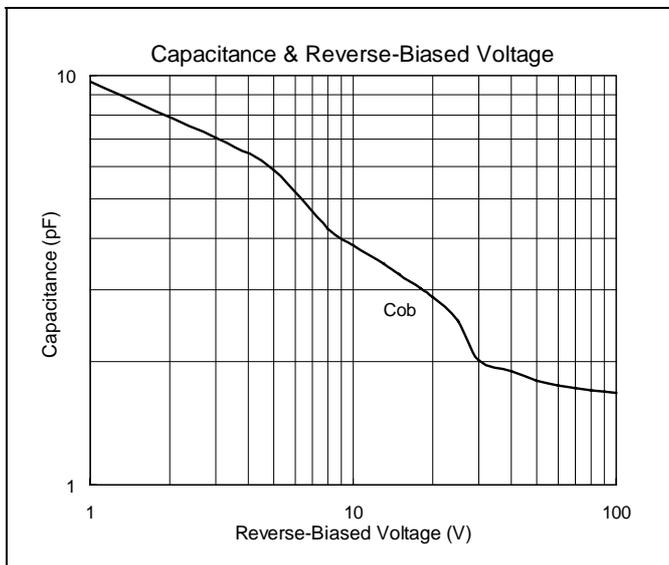
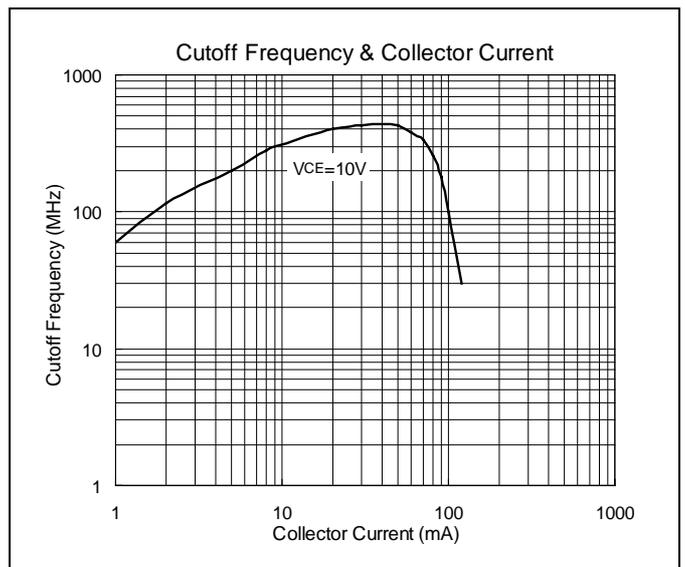
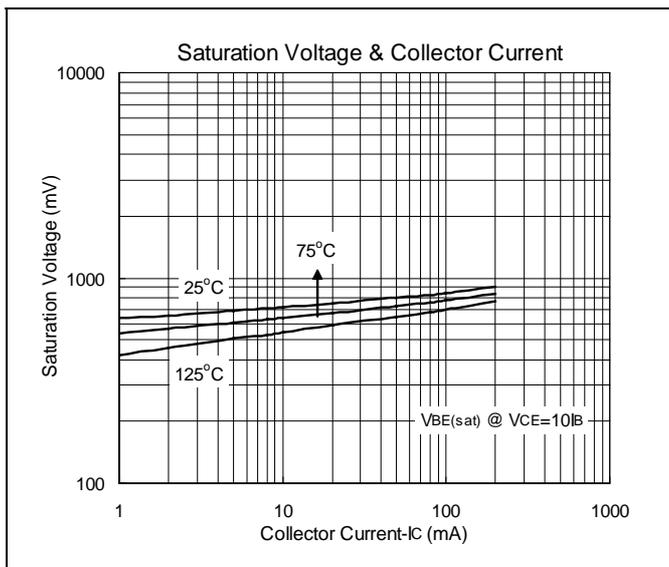
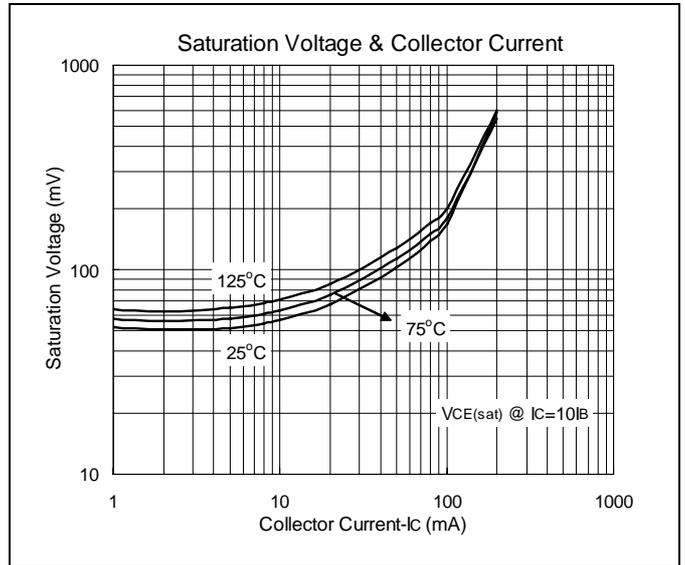
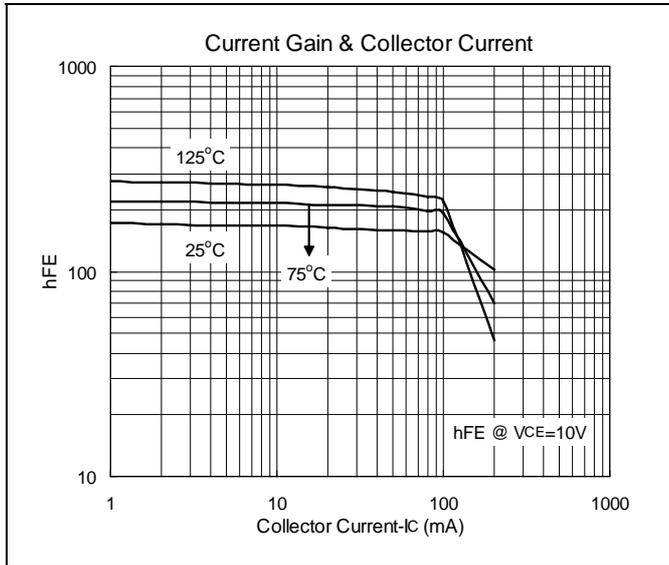
\*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

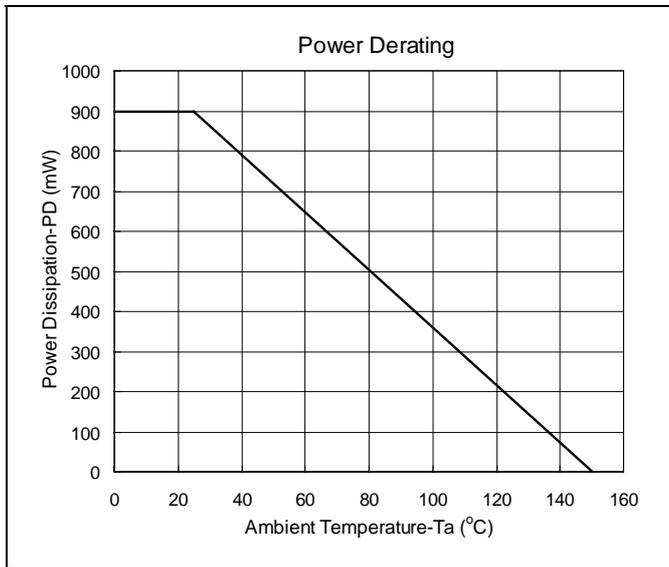
## Classification Of hFE1

Rank	D	E	F
Range	60-120	100-200	160-320



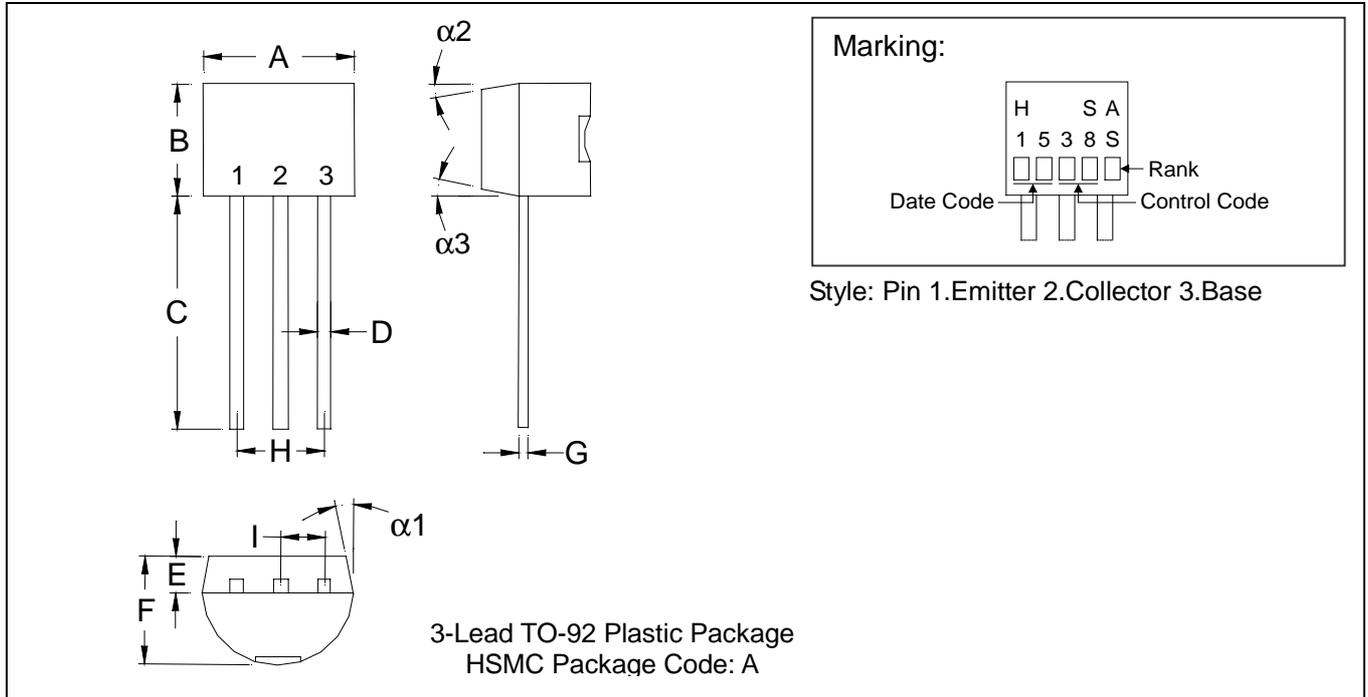
### Characteristics Curve







### TO-92 Dimension



\*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	$\alpha 1$	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	$\alpha 2$	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	$\alpha 3$	-	*2°	-	*2°

- Notes:**
- 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.
  - 2.Controlling dimension: millimeters.
  - 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
  - 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

**Material:**

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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